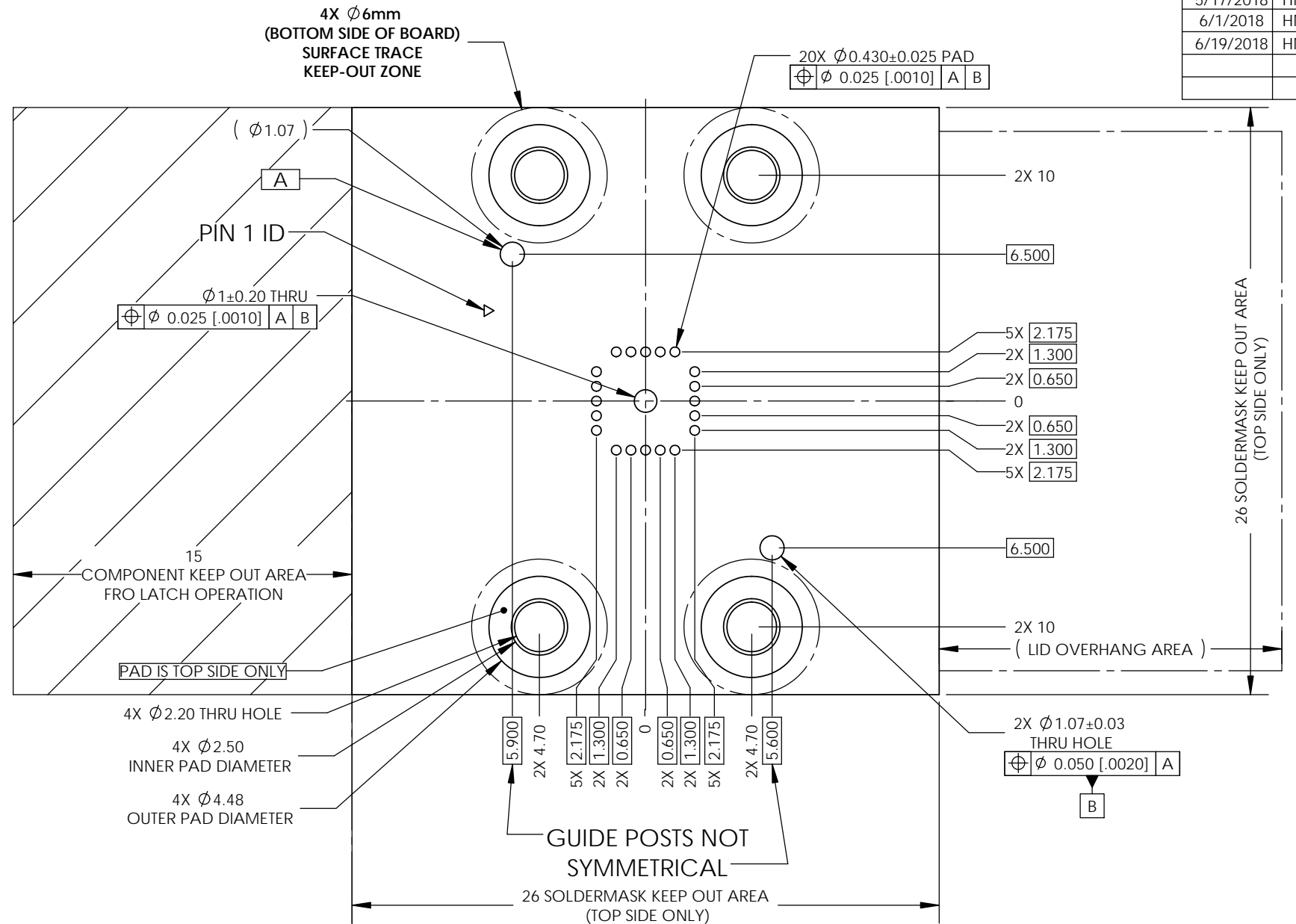
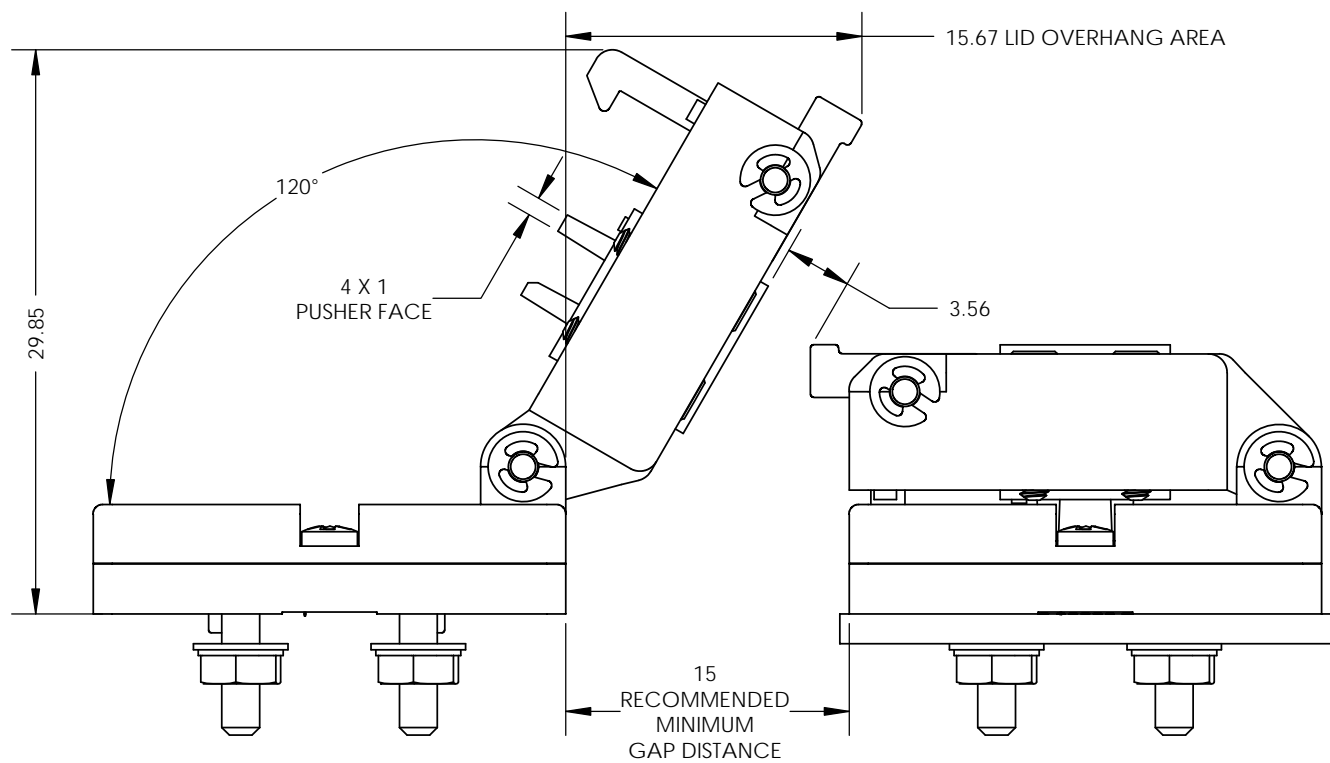
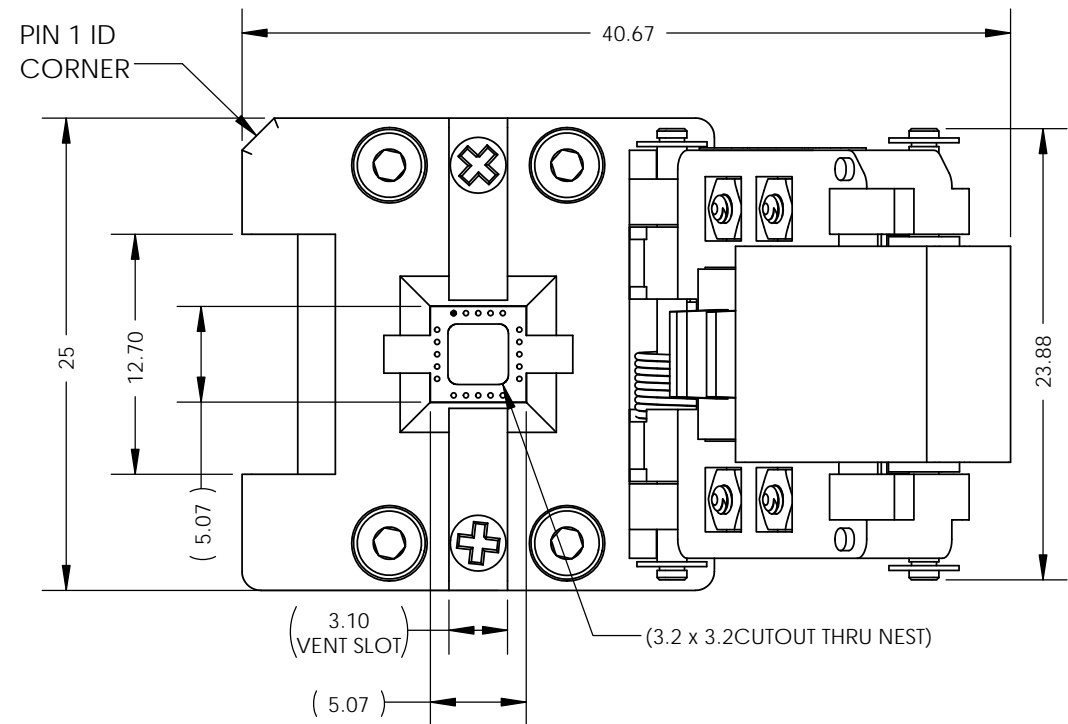


DATE	DRN
5/17/2018	HM
6/1/2018	HM
6/19/2018	HM



**TOP VIEW OF BOARD**

**NOTES:**

1. TOOLS REQUIRED FOR ASSEMBLY: 1.5mm ALLEN TORQUE DRIVER, 4mm HEX SOCKET DRIVER
2. PCB PAD PLATING: 30 µin. HARD Au OVER 300 µin. Ni OVER 1oz. MIN. Cu
3. CONTACT PLATING: 30 µin. Au OVER 75 µin. Ni
4. PLASTIC MATERIAL: ULTEM 2210EPR
5. ALL Au PADS SHOULD BE SAME THICKNESS.
6. BOARD LAYOUT TOLERANCE: ± 0.05mm.
7. FILLED VIAS ARE ACCEPTABLE PROVIDED FILLER MATERIAL CAN WITHSTAND CONTACT FORCE AT BURN-IN TEMPERATURE.
8. SOCKET SHOULD FIT FREELY INTO PCB.

**FEATURES:**

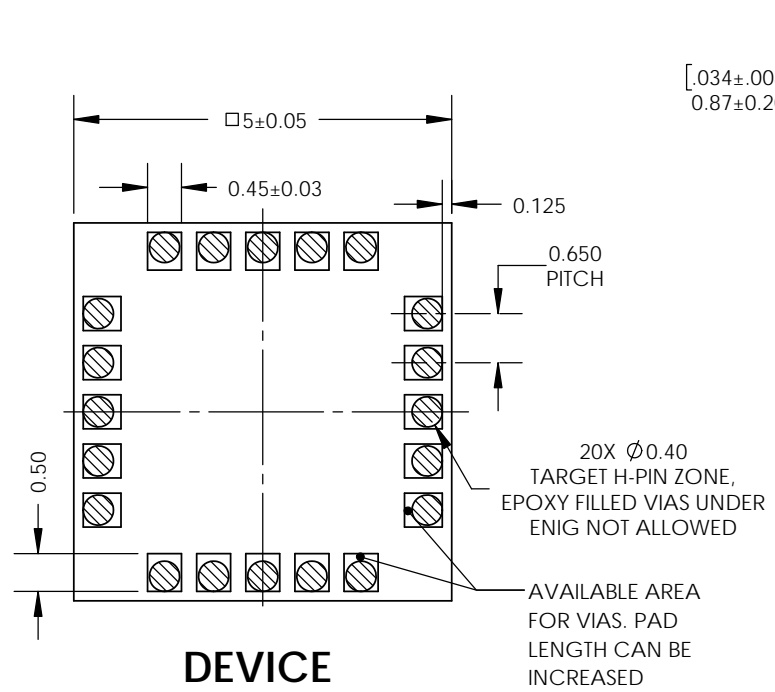
- CONTACT = H038LL1A (31gF)
- MOLDED CONTACT HOLES
- OVERSIZED NEST
- TWEEZER SLOTS
- VENTING THRU SOCKET AND PCB
- HORIZONTAL VENTING IN NEST
- FLOATING PLASTIC PUSHER (2 FINGERS)
- THRU HOLE IN PUSHER & PUSHER COVER
- 4X CLEARANCE CUTS THRU BOTTOM PLATE
- PRODUCT NAME: CD3710

**CODE NAME: CD3710**

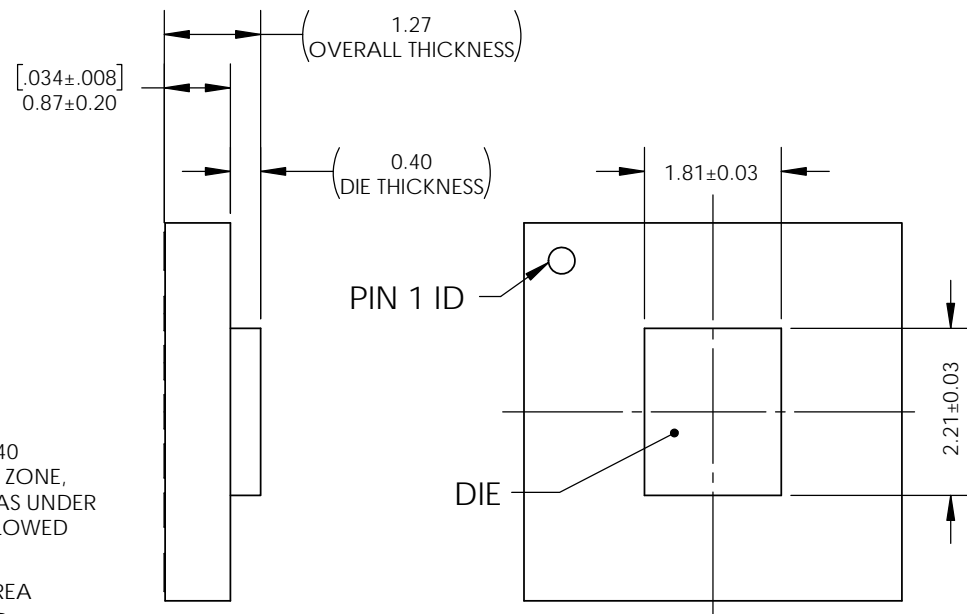
**P/N: 20QHC65Y85050G**

**PROPRIETARY**

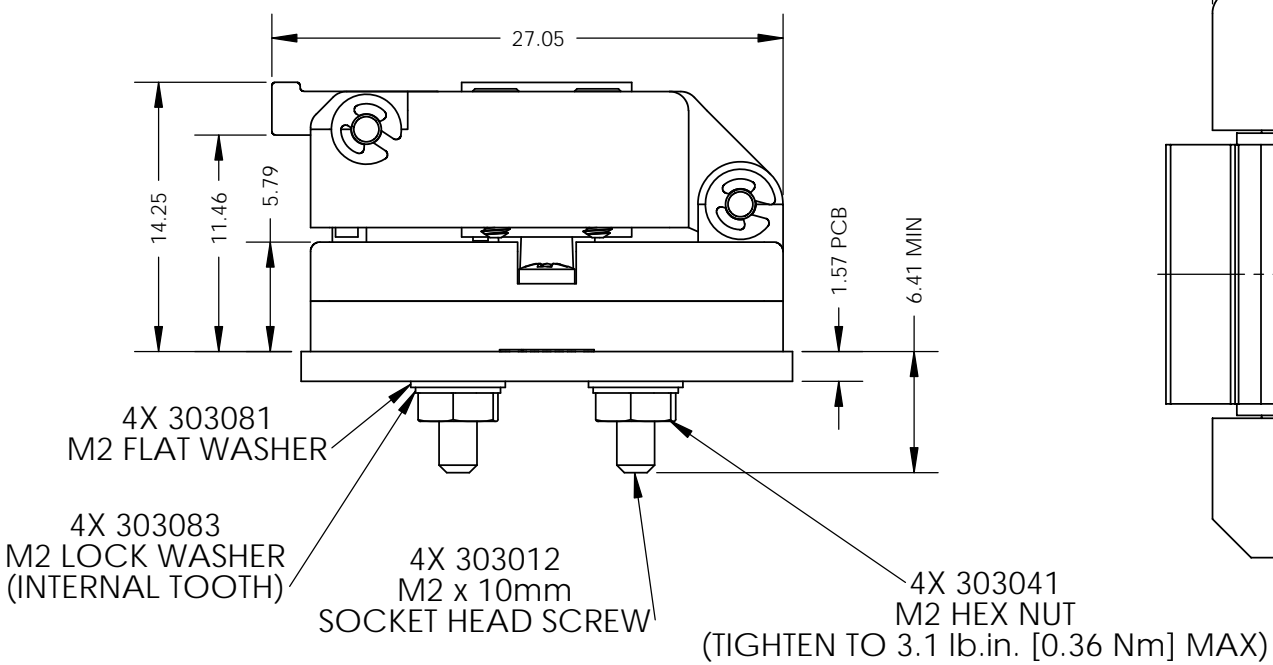
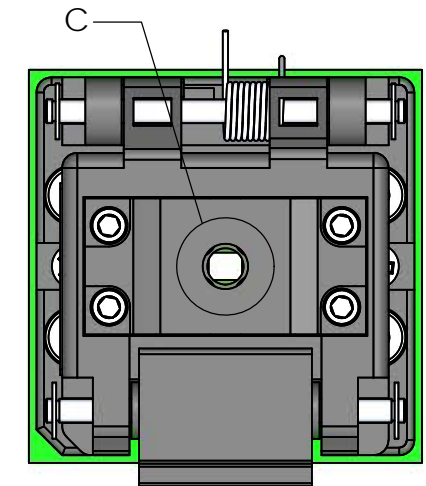
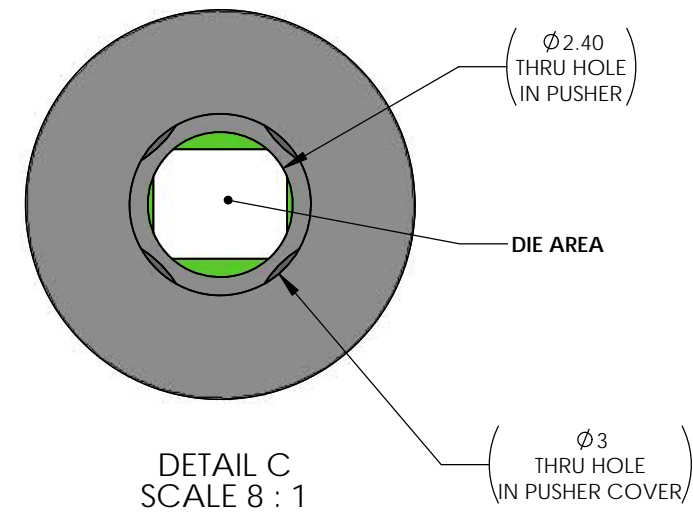
THIS DRAWING IS SUBJECT TO CHANGE WITHOUT NOTICE. PLEASE REQUEST A CURRENT DRAWING WHEN LAYING OUT BOARDS.	SIZE: B	NAME	DATE	DWG NO. <b>S20QHC65Y85050G</b>	SHEET 1 OF 2
	DRAWN	HM	5/17/2018	TITLE:	
SCALE: VARIOUS	CHECKED	JRM	5/17/2018	C SERIES QFN, 5.0 x 5.0mm DEVICE, 0.65mm PITCH, 20x 0.50mm H-PINS	
UNITS: mmgs	ENG APPR.				
SOLIDWORKS CREATED FILE	MFG APPR.				



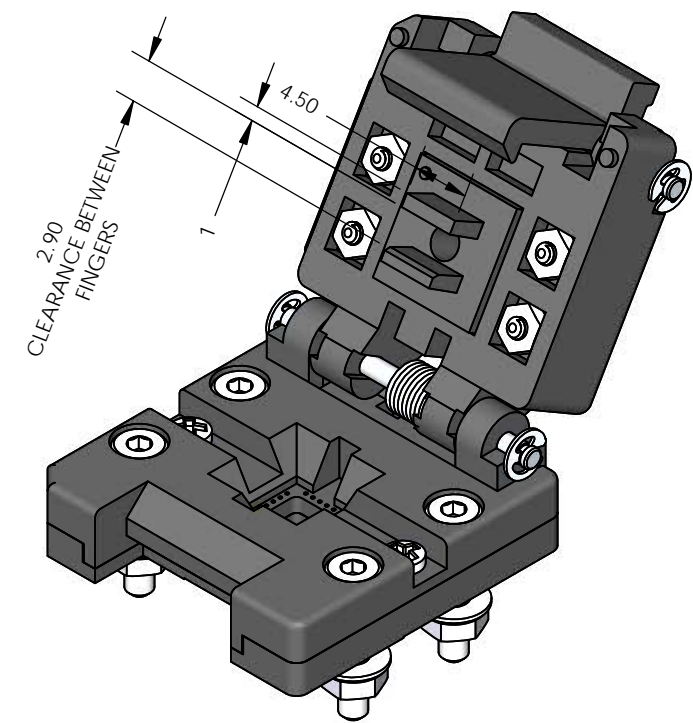
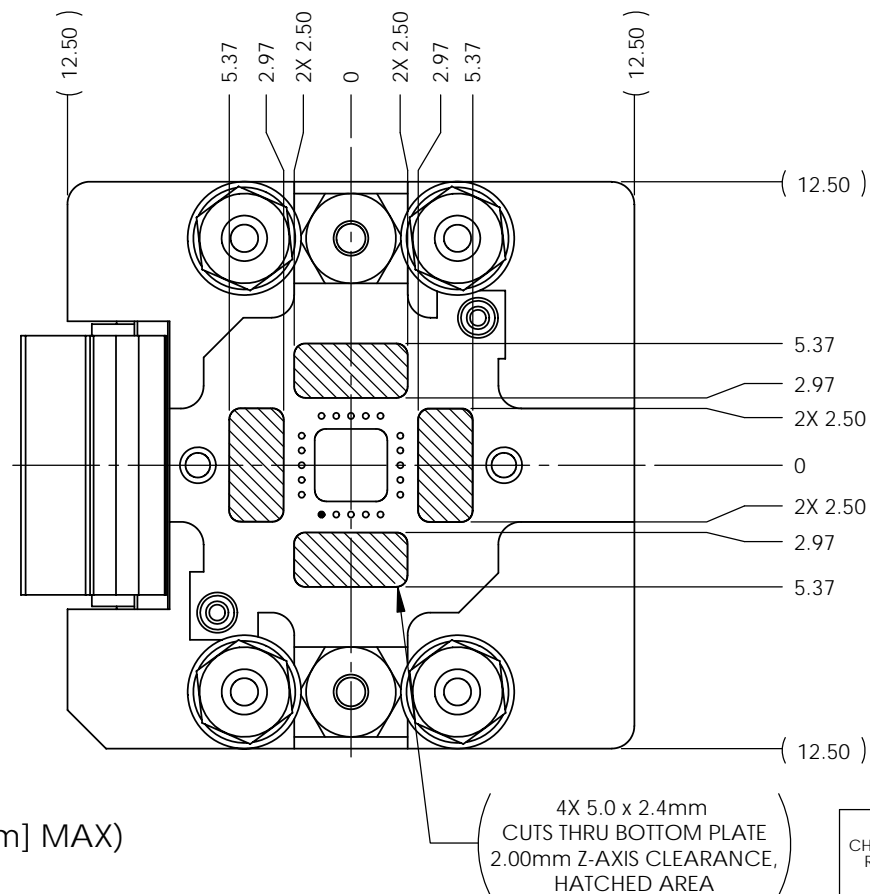
**DEVICE  
BOTTOM VIEW**



**DEVICE  
TOP VIEW**



**BOTTOM VIEW  
OF SOCKET**



**CODE NAME: CD3710**

**P/N: 20QHC65Y85050G**

**PROPRIETARY**

THIS DRAWING IS SUBJECT TO CHANGE WITHOUT NOTICE. PLEASE REQUEST A CURRENT DRAWING WHEN LAYING OUT BOARDS.	SIZE: B	NAME: HM	DATE: 5/17/2018	DWG NO. S20QHC65Y85050G	SHEET 2 OF 2
	DRAWN	CHECKED: JRM	5/17/2018	TITLE: C SERIES QFN, 5.0 x 5.0mm DEVICE, 0.65mm PITCH, 20x 0.50mm H-PINS	
SCALE: VARIOUS	ENG APPR.				
UNITS: mmgs	MFG APPR.				
SOLIDWORKS CREATED FILE					